



THE VISION Atom Chip



## neutral-atom manipulation using integrated micro-devices

## combining the best of two worlds:

- cold neutral atoms a well controllable quantum system
- technologies of nano-fabrication, micro-electronics, micro-optics

Take the tools of quantum optics and atomic physics and make them robust and applicable by miniaturizing and integrating them using the techniques of nano-fabrication, micro-electronics and micro-optics.

 create a tool box for building quantum devices





# MINIATURIZATION and INTEGRATION















mesoscopic matter wave optics similar to quantum electronics

# Microscopic potentials

- Atom Chip: integrated mesoscopic matter wave devices
- Atoms close to warm surfaces
- Atom Optics on Atom Chip
- Atom detectors

R. Folman et al. Adv.At.Mol.Opt.Phys. 2002

**Review:** 

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# Interactions for micro traps



#### **Magnetic Potentials**

Magnetic moment of the atom interactiong with the magnetic field

$$U_{mag} = -\vec{\mu} \cdot \vec{B}$$

 $U_B[\mu K] \propto 67 B$  [G] strong field seeker: weak field seeker:

#### Electric Potentials

Electric polarizability interacting with an electric field

$$U_{el} = -\frac{1}{2}aE^2$$

Li-Atom:  $\alpha$ =24A<sup>3</sup>  $U_E[\mu K] \propto 98 E^2[V/\mu m]$ 



For a review see R. Grimm et al. Adv. At. Mol. Opt. Phys. 42, 95-170 (2000).



## MAGNETIC INTERACTION $U_{mag} = -\vec{\mu} \cdot \vec{B}$



### **Quantum wire:**

current carrying wire

 $\vec{B}(\rho) \propto I \frac{1}{\rho} \hat{e}_{\varphi}$ 

**Vector Coulomb Problem** 

adding a bias field creates a potential minimum on side of wire (Frisch, Segre 1932)

potential depth:bias fieldpotential gradient:1/I

Mount wire on a surface: Use nanofabrication to build mesoscopic structures.







Vladimirskii Sov. Phys. JETP 12, 740 (1961) Experiment:Schmiedmayer IQEC 92; PRA 52, R13 (1995) Denschlag et al. PRL 82, 2014 (1999) strong field seeker: U<sub>mag</sub>< 0







Achievable: level spacing of >1 MHz



# DESIGNS Surface Mounted Atom Optics



Guides with external bias field

⊗ ⊙ with on chip bias field





4-wire 3-wire















Classical Trajectories No stable orbits!

Totential  
The formula  

$$U_{INT} = -\frac{1}{2}\alpha E^{2} = -\frac{2\alpha q^{2}}{r^{2}}$$
Angular momentum  

$$U_{Lz} = \frac{L_{z}^{2}}{2Mr^{2}}$$
Total potential  

$$U_{Eff} = U_{L_{z}} + U_{INT}$$

$$= \frac{1}{2Mr^{2}} \left[ L_{z}^{2} - L_{crit}^{2}(q) \right]$$
Critical angular momentum:  

$$L_{crit} = 2\sqrt{\alpha M} q$$





### Decay experiments 3 different wire diameters



## Measuring the fall onto the wire by trap devay





Denschlag et al. PRL 81, 737 (1998)



R. Folman et al. Adv.At.Mol.Opt.Phys. 2002

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## Adapted nanofabrication technique to needs

#### of Atom Chip (Weizman, Innsbruck/Heidelberg, TU-Vienna)

#### **Features:**

- Chip = mirror  $\rightarrow$  wires are defined by etchings
- structures down to 1 μm
- current densities  $> 3 \ 10^7 \ \text{A/cm}^2$
- high voltages > 500V
- trap frequencies > 1MHz ground state size ~10 nm
- multi layer possible

#### Other techniques (MPQ, Orsay, Tübingen ...):

250 nm]

25 µm

300 µm

Thin film hybrid technology

- Larger structures
- Large cross section
- High currents











### Atom Chip Fabrication S. Groth et al. Cond-mat/0404141 (2004)



Innsbruck, Heidelberg, Weizmann, TU-Wien

Adapted from standard semiconductor nanofab.





2001



S. Groth et al. Cond-mat/0404141 (2004)





![](_page_10_Figure_1.jpeg)

![](_page_11_Picture_0.jpeg)

# ATOM CHIP STATUS experiments with thermal atoms

![](_page_11_Picture_2.jpeg)

![](_page_11_Picture_3.jpeg)

![](_page_11_Picture_4.jpeg)

# INTERFEROMETER on the Atom Chip

![](_page_11_Figure_6.jpeg)

#### Experiment with thermal atoms

![](_page_11_Figure_8.jpeg)

![](_page_11_Figure_9.jpeg)

Problem: minimum of the potential changes during the splitting.

## Manipoulation with Electric Fields

![](_page_12_Picture_1.jpeg)

![](_page_12_Figure_2.jpeg)

![](_page_12_Picture_3.jpeg)

Heidelberg

† 1

Trapped T = 2 μK

2 mm

# BEC in MICRO TRAP

16 ms exp < 600 nK, BEC

0

Cu. Chip substrate and surface (not to scale)

16 ms exp 600 nK, bimodal

16 ms exp

= 2 µK, thermal

![](_page_12_Picture_5.jpeg)

Heidelberg

Many groups: Tübingen, MPQ, ORSAY, IC, MIT, JILA, Brisbane ...

With a BEC we have a reservoir of motional ground state atoms as a source for the experiments

#### High atom density

- -> the matter wave optics will be non linear
- -> if interactions dominate: strongly correlated systems

MOT > 3 10<sup>8</sup> atoms @ 70  $\mu$ K Magn. Z trap > 10<sup>8</sup> at. @ 250  $\mu$ K Compress trans.: ~500 Hz ~400 G/cm long.: ~ 50 Hz RF-Evaporation ~10 sec BEC 3 10<sup>5</sup> atoms @ T<sub>c</sub> ~ 500 nK Independent of chip structure

![](_page_13_Picture_0.jpeg)

![](_page_13_Picture_1.jpeg)

# Why go close to surface

![](_page_13_Picture_3.jpeg)

- Tight confinement (transversal)
   1d-physics, QuInfo
   Confinement proportional to current density j
   j depends on the removal of Ohmic heat better for small wires
- Small potentials for tunnelling coupling
  - Minimum structure size of the potentials
     ~ distance to the surface
  - size ~ 1µm

. . . . . . . .

- Small potentials for quantum tweezer loading single atoms
- Manipulating mesoscopic ensambles

![](_page_14_Figure_0.jpeg)

![](_page_14_Figure_1.jpeg)

![](_page_15_Figure_0.jpeg)

![](_page_15_Picture_1.jpeg)

# From where do the disorder potentials come from

- Atoms are trapped in the minima of potentials created by the subtraction of two large fields.
- Minimum in that plane depends on the angle between these two fields.
- Sensitivity to changes in the current direction which are **not** orthogonal to the bias field.
- Sensitivity: thermal atoms: 1G ~ 67  $\mu$ K BEC: chem. potential (~1-10 mG) sensitivity < 10<sup>-5</sup> rad

![](_page_15_Figure_8.jpeg)

Proposal:

- Roughness of the wire edge causes the current to deviate from a straight flow (we choose evap. gold and nanofab.) for theory see: Daw-Wie Wang et al. PRL 92, 076802 (04).
- Imperfections in the surface of substrate (we chose Si and GaAs).
- Disordered current flow due to grain size, inhomgeneities, ... in the wire.

![](_page_16_Figure_0.jpeg)

![](_page_16_Picture_1.jpeg)

![](_page_16_Figure_2.jpeg)

![](_page_16_Figure_3.jpeg)

![](_page_16_Picture_4.jpeg)

![](_page_16_Picture_5.jpeg)

Fragmentation becomes visible typical scale given by chem. potential of BEC (~100nK)

![](_page_16_Figure_7.jpeg)

- •Wire can be scanned by variation of longitudinal confinement
- •disorder potentials are stable in position and time

![](_page_16_Picture_10.jpeg)

![](_page_17_Picture_0.jpeg)

![](_page_17_Picture_2.jpeg)

Possible sources:

- gravitation (~100nK/µm)
- electric fields
- magnetic fields (irregular currents)

![](_page_17_Figure_7.jpeg)

scan at equal height but varied currents

disorder potentials normalized to  $\Delta B/B$ 

traces equal within  $\Delta B/B \sim 3 \ 10^{-6}$   $\Delta U < 10^{-13} \, eV$  down to d<5  $\mu m$ 

![](_page_17_Picture_11.jpeg)

![](_page_18_Figure_0.jpeg)

![](_page_19_Picture_0.jpeg)

![](_page_19_Picture_2.jpeg)

![](_page_19_Figure_3.jpeg)

Scaling of disorder potentials near a broad wire (100µm)

- fragmentation increases as the surface (not edge) is approached
- pure edge effect leads to different scaling
- Simple local model gives better agreement
- k-dependence  $\sim 1/k^2$

![](_page_19_Picture_9.jpeg)

![](_page_20_Picture_0.jpeg)

# Trap independent disorder probe

![](_page_20_Picture_2.jpeg)

BEC can be placed far from trapping wire but close to a different structure by rotating the bias field Atoms held with 10µm wire above 100µm wire

![](_page_20_Figure_4.jpeg)

![](_page_20_Picture_5.jpeg)

![](_page_21_Picture_0.jpeg)

# Condensing with E-field

![](_page_21_Picture_2.jpeg)

![](_page_21_Figure_3.jpeg)

![](_page_21_Figure_4.jpeg)

![](_page_21_Figure_5.jpeg)

![](_page_22_Picture_0.jpeg)

# Condensate formation in dimple trap

![](_page_22_Picture_2.jpeg)

- thermal atoms just above  $T_{\rm C}$  in a 1d trap
- at 0ms electric dimple is suddenly created
- 1d BEC forms slowly
- BEC becomes larger and 3d
- equilibrium reached after ~80ms

![](_page_22_Picture_8.jpeg)

![](_page_22_Figure_9.jpeg)

![](_page_23_Picture_0.jpeg)

# BEC propagation in 1d guide against a background

![](_page_23_Picture_2.jpeg)

![](_page_23_Picture_3.jpeg)

TOF = 16msDuration of sequence 5ms

- BEC is formed in 3d dimple
- off-center release to elongated (1d) trap by sudden  $(<1\mu s)$  switching off of dimple voltage
- background gas temperature ~T<sub>c</sub>
- movement of edge at ~5cm/s
- thermalization into equilibrium state (centered cloud at  $T_c$ ) on slower time scale (~100ms)

![](_page_23_Figure_10.jpeg)

![](_page_24_Picture_0.jpeg)

![](_page_25_Picture_0.jpeg)

# INTEGRATION OF LIGHT ON THE ATOM CHIP

![](_page_25_Picture_2.jpeg)

**Goals:** Preparation, Manipulation, Detection of atomic states on the Atom Chip **Tools:** Micro optics: cavities, lenses, waveguides

**Techniques of coupling to the atoms:** Two mirror resonators, evanescent fields of micro spheres or micro discs, SNOM techniques, fiber cavities

![](_page_25_Figure_5.jpeg)

State selective, non-demolishing, single atom detection; Integration of all micro optical elements, including light sources, onto the Atom Chip

![](_page_25_Figure_7.jpeg)

![](_page_26_Picture_0.jpeg)

### Experiment with a macroscopic cavity

![](_page_26_Picture_2.jpeg)

#### **Test Setup**

![](_page_26_Figure_4.jpeg)

# Detecting Atoms in micro traps First signals

![](_page_26_Picture_6.jpeg)

#### Heidelberg Regime of bistability

![](_page_26_Figure_8.jpeg)

Cavity with Finess ~500 w~12  $\mu$ m

![](_page_27_Picture_0.jpeg)

# First fiber cavity test experiments

![](_page_27_Picture_2.jpeg)

![](_page_27_Picture_3.jpeg)

Fibre cavity of finesse 110 formed by dielectric mirrors at the outer fibre ends. A gap of 5 microns is included. The cavity length is scanned using a piezo stretcher, no alignment needed

 $8\sigma$  detection of a single atom in 10  $\mu$ s

Finess > 1000, w~2.5  $\mu$ m with front mirrors and gap up to  $>50 \ \mu m$ 

![](_page_27_Picture_7.jpeg)

# CONCLUSION

Atom Chip fabrication including integration of light on the Atom Chip

- Load versatile atom traps > surpassed the required ground state sizes for QIPC
  - > multiple traps, transport, gubit selective manipulation > BEC on Atom Chip

### Small disorder potentials -> mesoscopic exp.

- Controllable electric and magnetic disorder
- > New tool for surface physics

#### 1-d Experiments on Chip

- > 1-d thermal cloud (T~ħω)
- > 1-d BEC ( $\mu << \hbar\omega$ ) up to  $\gamma \sim 0.1$
- > BEC far from equilibrium, look at dynamics of phase trans.
- > BEC formation in disordered potentials
- Detector designs for  $>3\sigma$  in 10 µs
  - Detection of guided atoms with a cavity

Folman et al. Adv.At.Mol.Opt.Phys. 2002

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![](_page_28_Figure_0.jpeg)

Atom Chip Experiment Peter Krüger Stephan Wildermuth Elmer Haller Sebastian Hofferberth Mauritz Anderson

Atom Chip Detector Albrecht Haase Marco Wiltzbach Bjorn Hessmo

Atom Chip Fabrication Sönke Groth Israel Bar Joseph (WIS)

#### Former:

K. Brugger, D. Cassetari, R. Folman, X. Lou series of undergrad students in Heidelberg

EU: ACQUIRE, ACQP, FASTnet DFG: QIPC, Cold Quantum Gases Landesstiftung BW

### Atoms being loaded into a spiral on the Atom Chip

![](_page_28_Picture_8.jpeg)

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